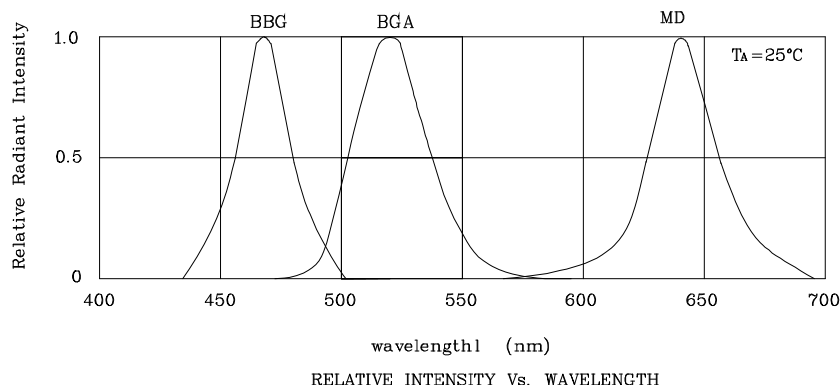
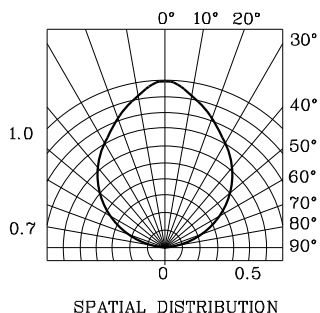
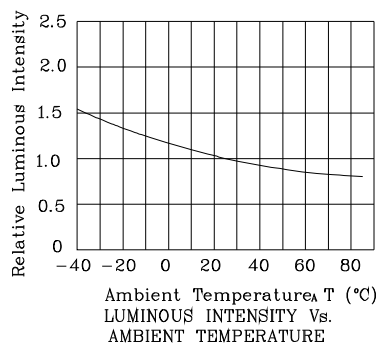
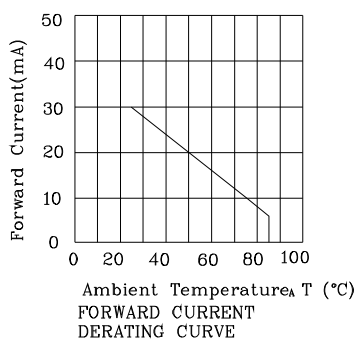
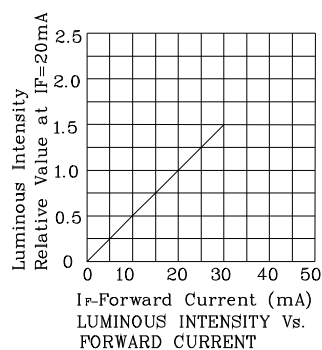
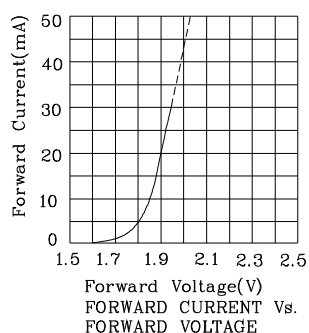
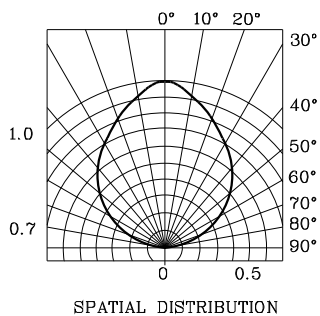
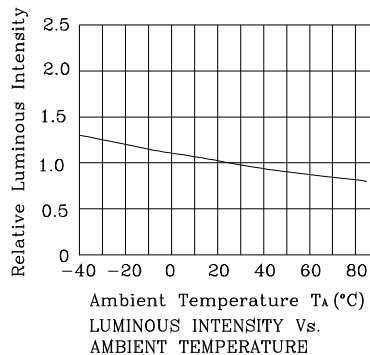
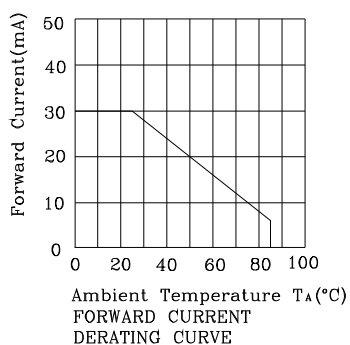
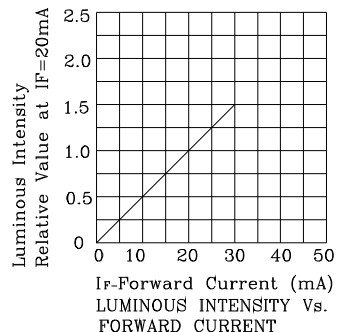
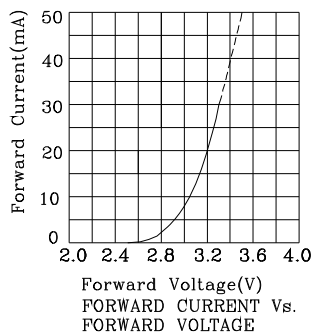




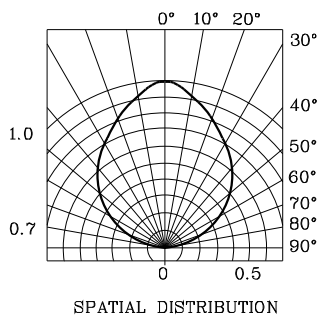
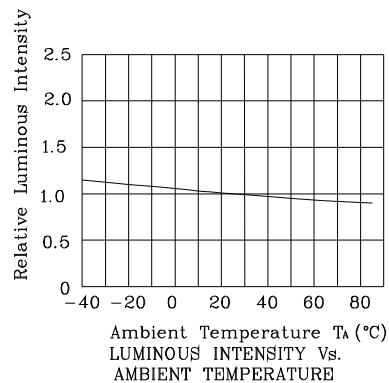
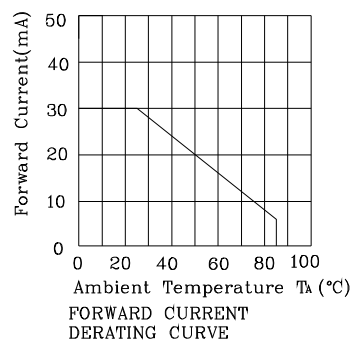
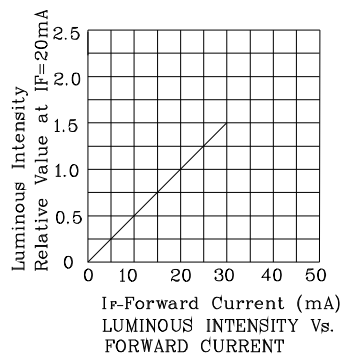
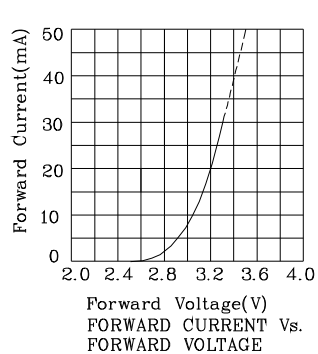
❖ MD



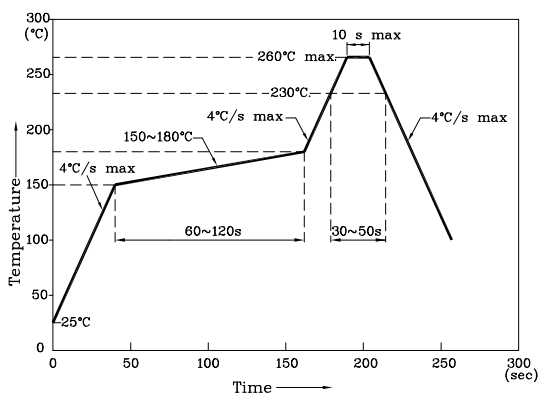
❖ BGA



❖ **BBG**



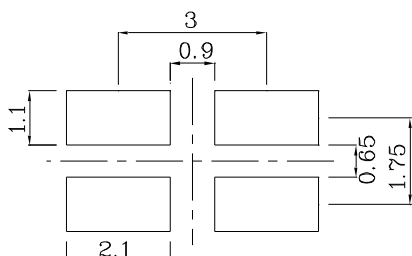
Reflow Soldering Profile For Lead-free SMT Process.



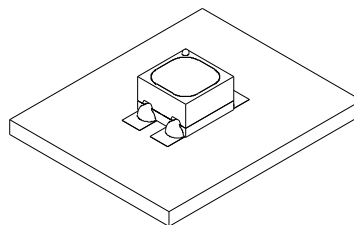
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

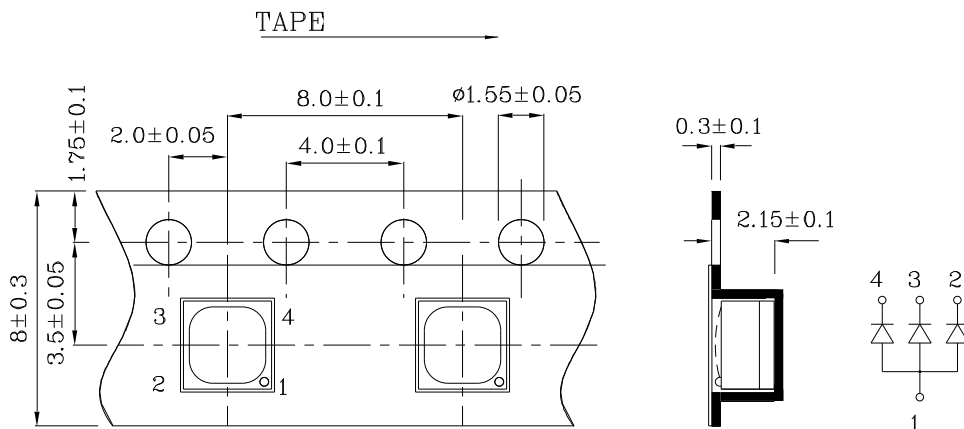
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ±0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

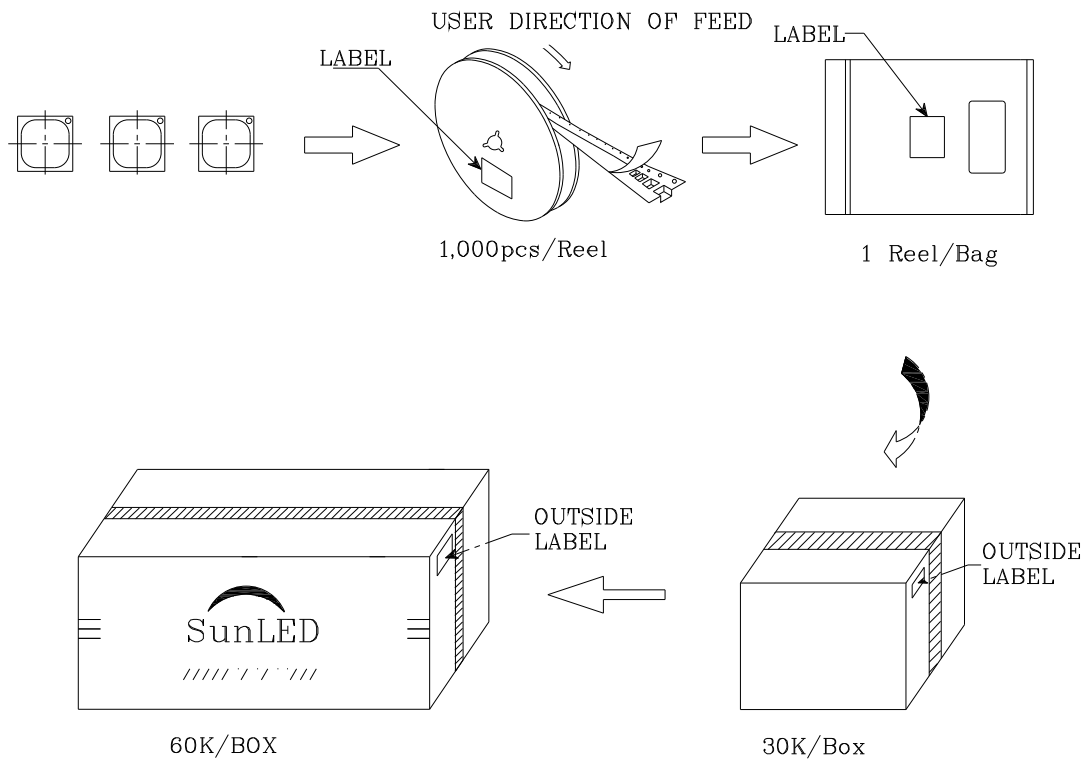
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

ZMDBGABBG86W





Q.C.
 Q C
 XX XX XXXX
 PASSED

P/NO : Zxxx86x	
QTY : 1,000 pcs	CODE: XXX
S/N : XX	
LOT NO :	
 XXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	